13

31

49

30

48

7n

Cd

AI

Ga

In

14

32

50

82

Si

Ge

Sn

Pb

51

83

Sb

Bi

# **APPLICATION NOTE**

# **Common Elements**

### **Aluminum**

Offers good corrosion resistance and good strength when alloyed with Zn or Si.

### **Antimony**

Increases tensile strength of solders. Poor conductor of heat and electricity.

### **Bismuth**

Low melting when alloyed with SnPb or In. Expands 3.32% on solidification. Non-toxic.

### **Cadmium**

Increases corrosion resistance of solders.

Increases service temperature and strength of solder.

## Copper

When used in SnPb alloys, slight increase in spread rate, lowers melting temperature.

29

47

Cu

Ag

Au

### Gallium

Has one of the longest liquid ranges for metals. Has low vapor pressure.

### Germanium

When alloyed with Au or Al, will reduce melting point and increase strength. Contributes to poor solder wettability.

### Gold

Highly conductive and corrosion resistant. High melting point is reduced when alloyed with Sn, Si, or Ge.

### Indium

Improves wetting of PbAg solders. Resists alkaline corrosion. Bonds glass, quartz, and glazed ceramics.

### Lead

Economical material, soft and ductile. Offers increased strength when alloyed with other elements. Toxic.

### Silicon

When used with Au or AI, will reduce melting point, increase strength, and improve wettability.

### Silver

Exhibits the highest electrical and thermal conductivity of all metals.

### Tin

Excellent wetting characteristics. Low strength when used alone but becomes stronger when alloyed.

### **Zinc**

When used in SnPb alloys, lowers spreading rate; when soldering to Al, used to reduce the electrical potential difference.

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